
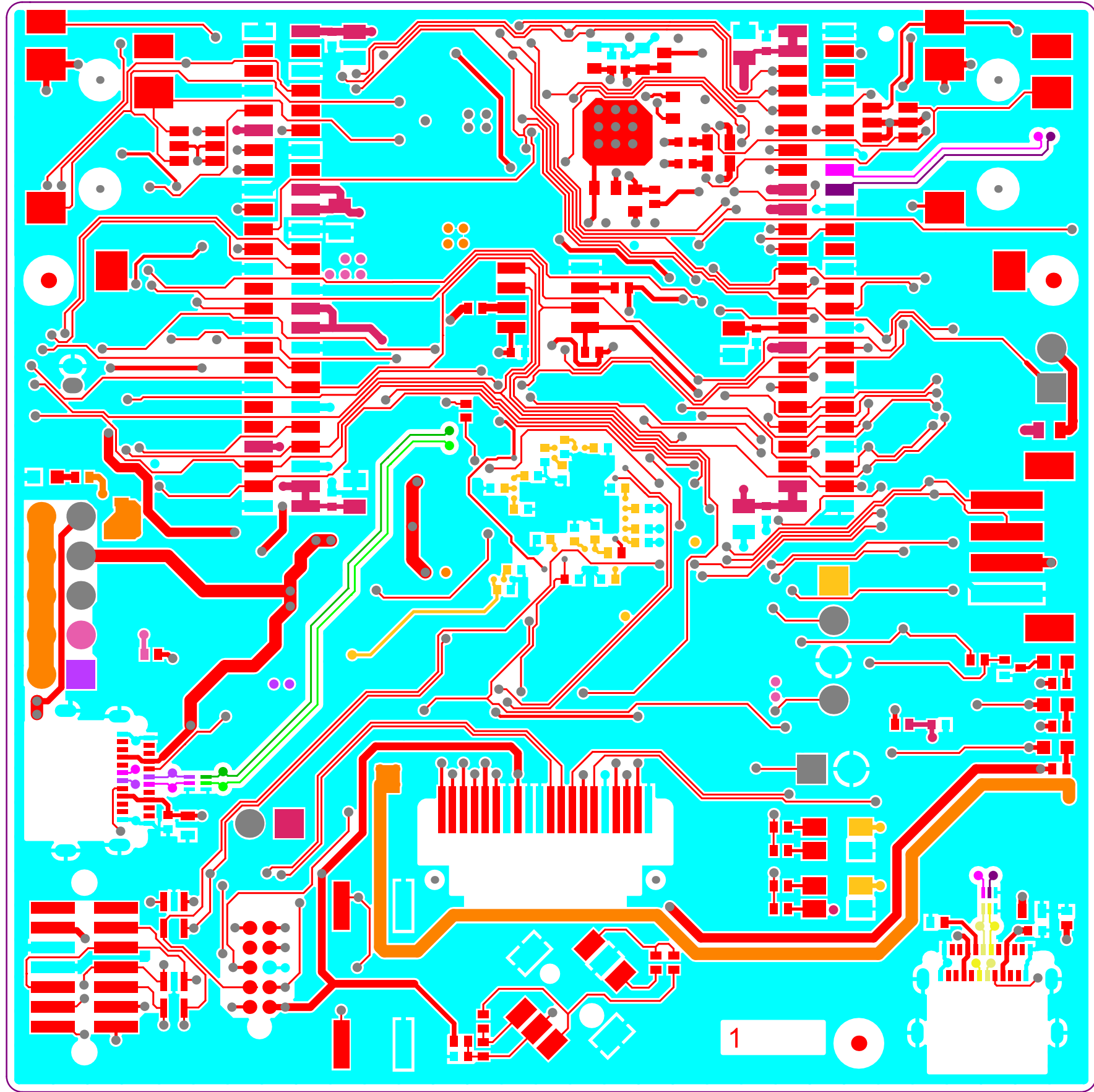

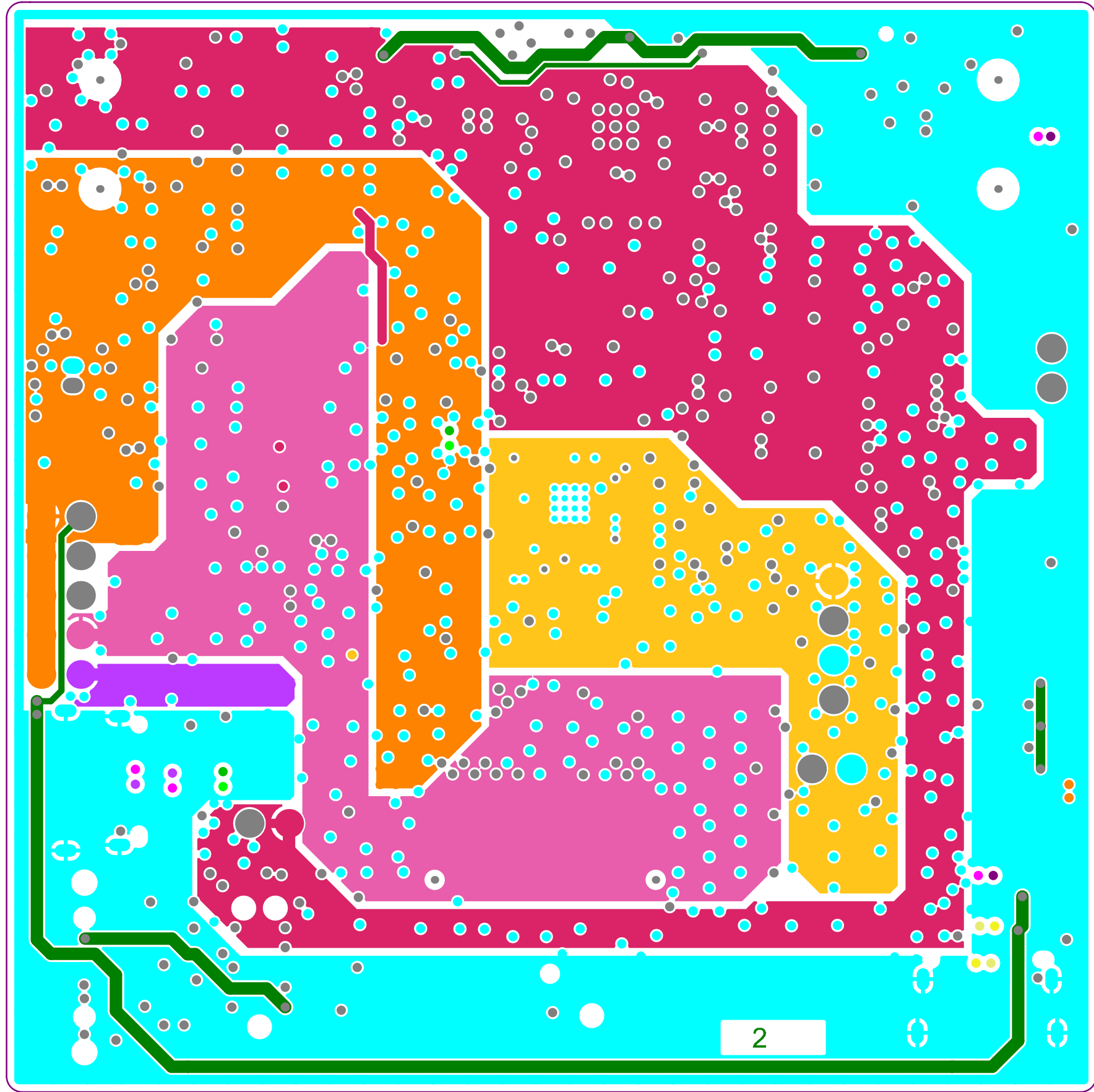



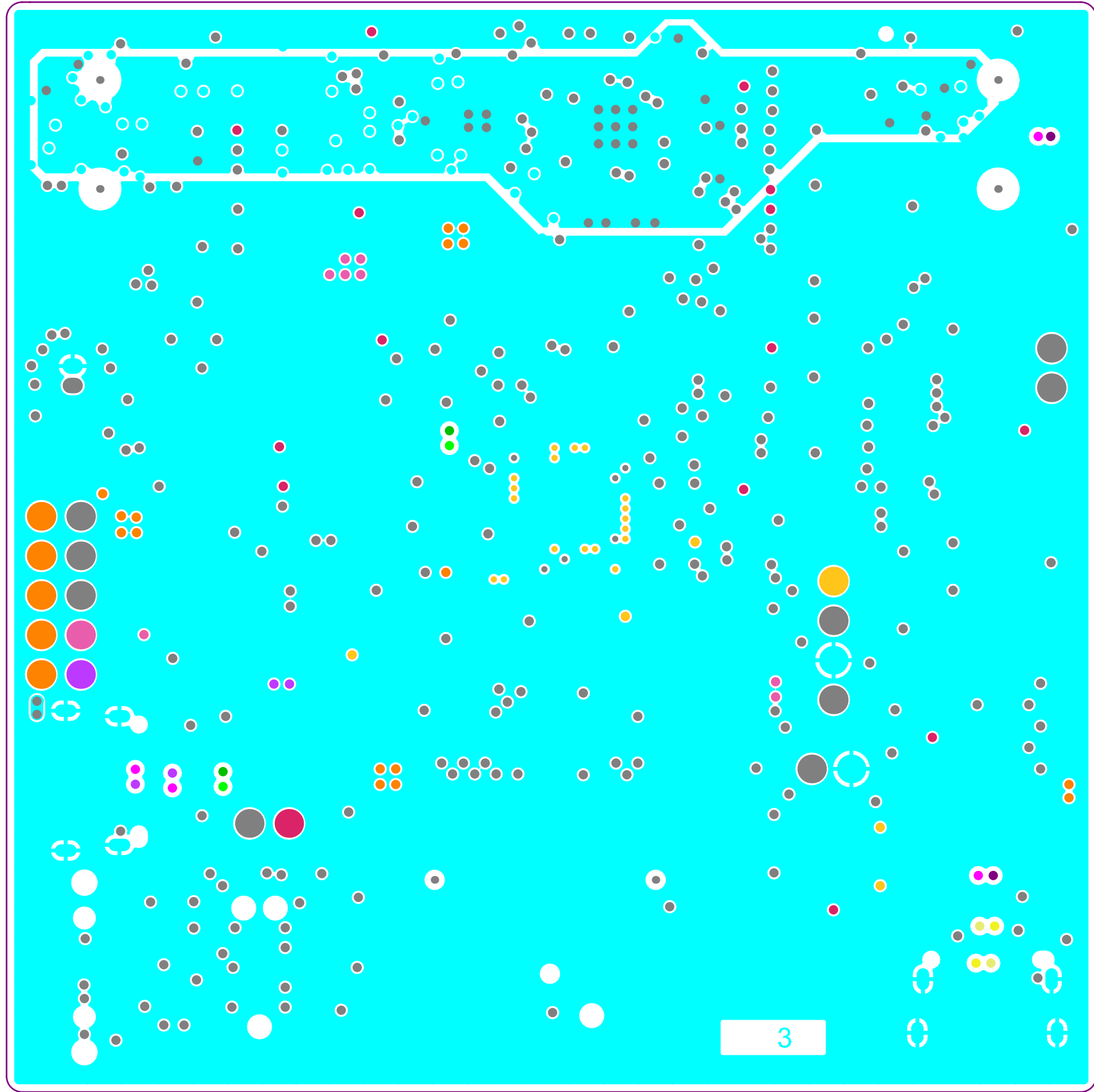
Project: STM32WBA65I-DK1		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	




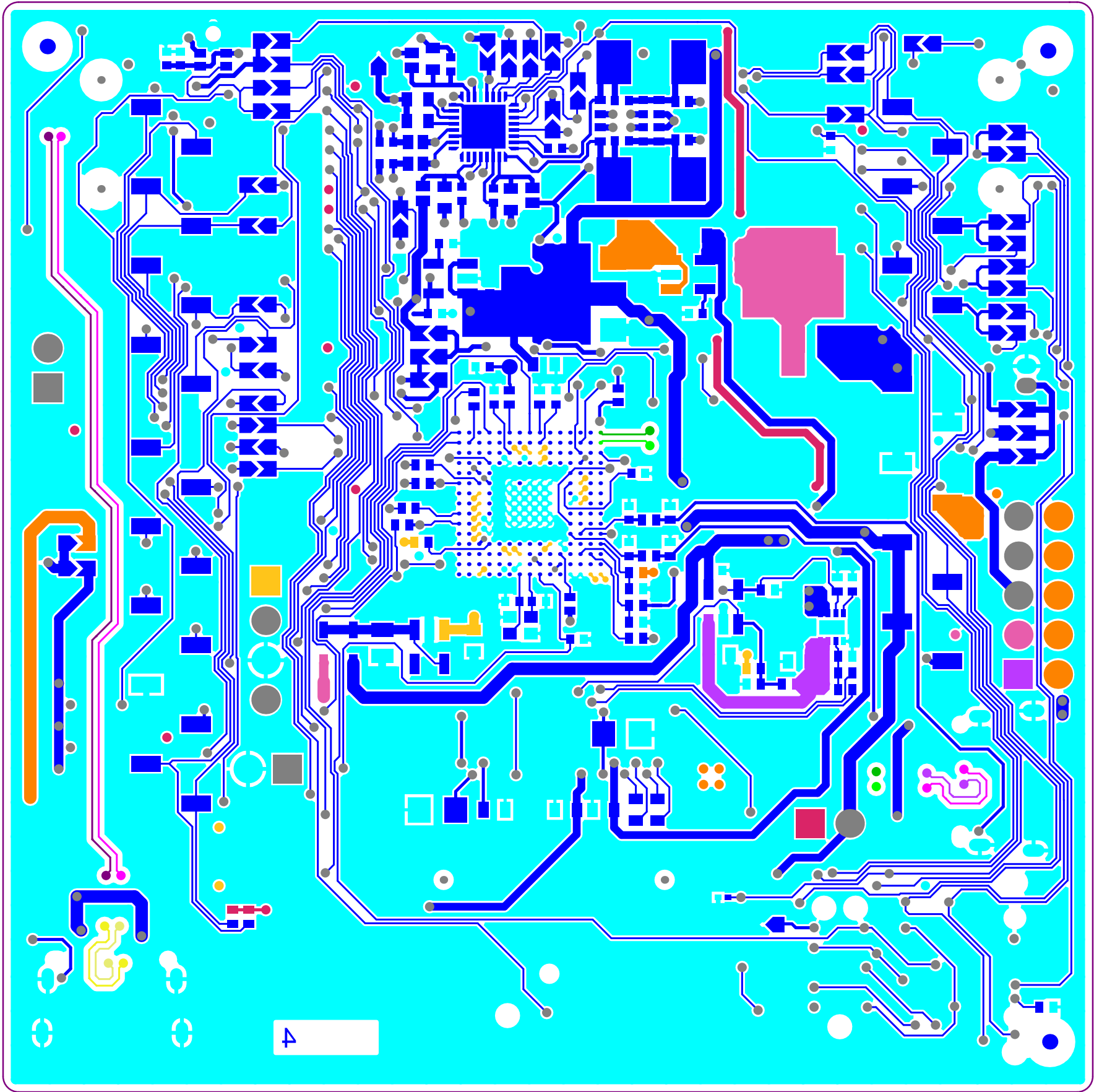
Project: STM32WBA65I-DK1		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	




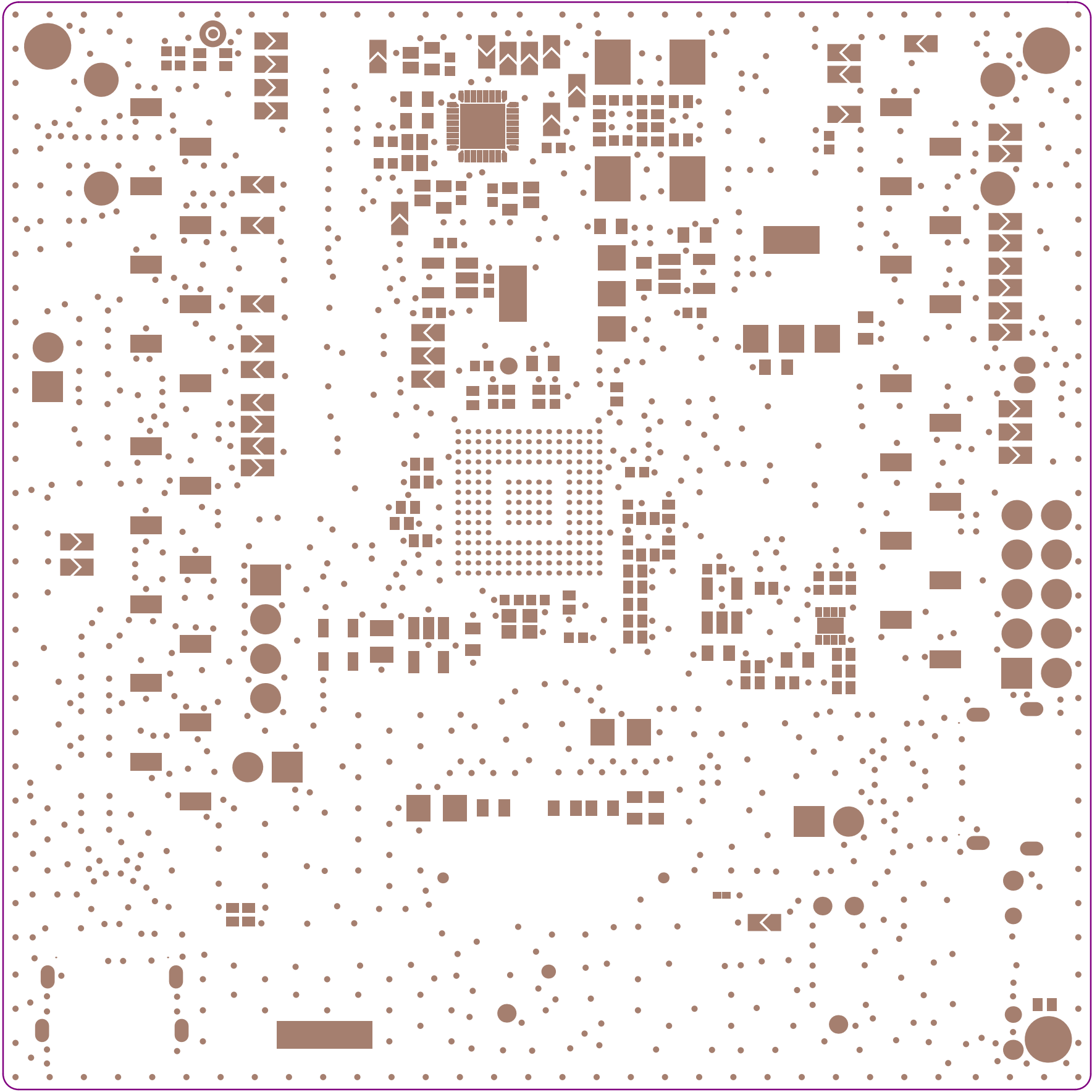
Project: STM32WBA65I-DK1		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	




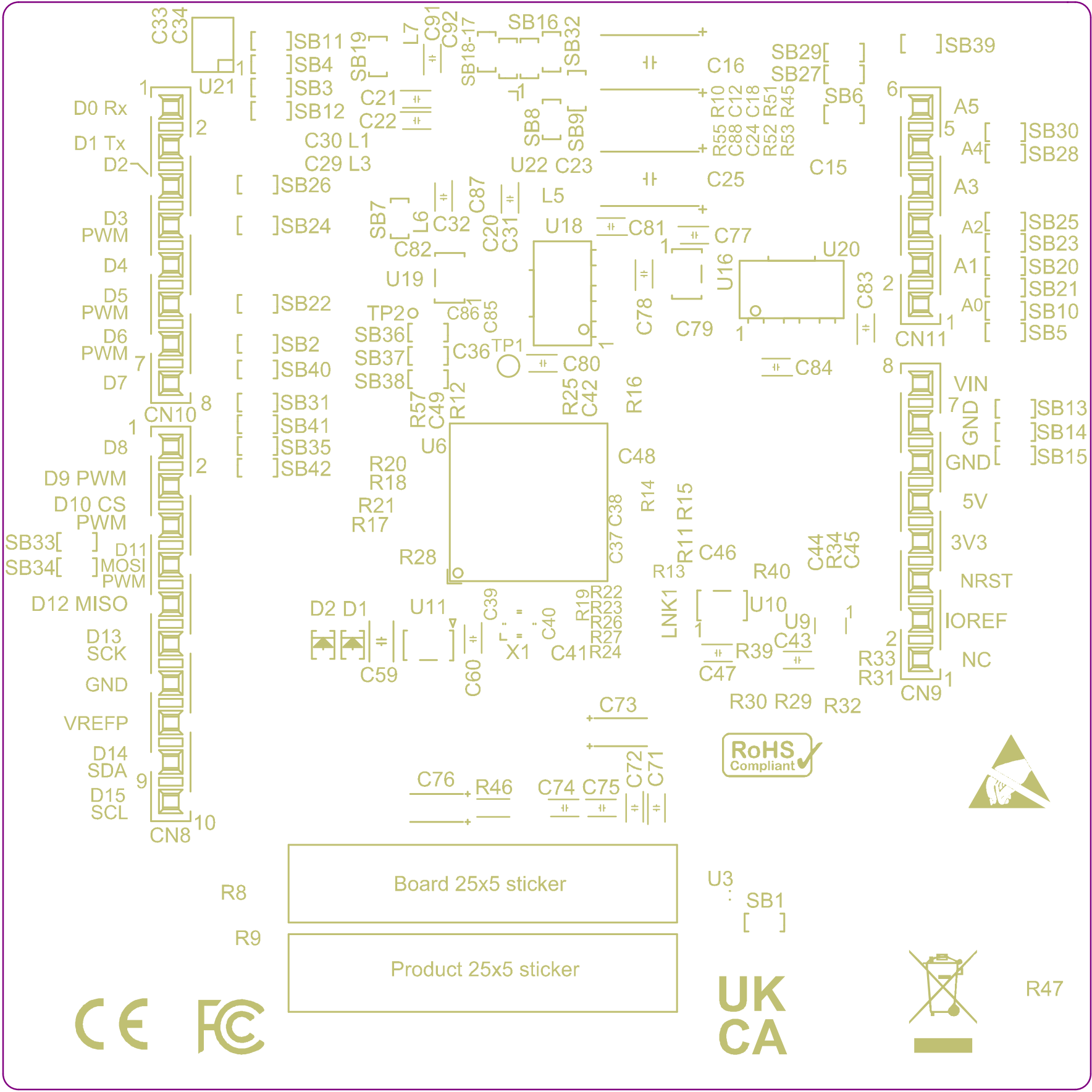
Project: STM32WBA65I-DK1		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	




Project: STM32WBA65I-DK1		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	



Project: STM32WBA65I-DK1		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	



Project: STM32WBA65I-DK1		
Layer: Bottom Overlay	Gerber: GBO	
Variant: [No Variations]	Ref: MB2143	
Date: 30-APRIL-24	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE XLS FILE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0,020mm	3.5
1	Top Layer		0,054mm	
	Dielectric 1	1080HR RC68	0,076mm	4.2
2	Signal Layer 1		0,035mm	
	Dielectric 2	FR4	1,230mm	4.5
3	Signal Layer 2		0,035mm	
	Dielectric 3	1080HR RC68	0,076mm	4.2
4	Bottom Layer		0,054mm	
	Bottom Solder	Solder Resist	0,020mm	3.5
	Bottom Overlay			

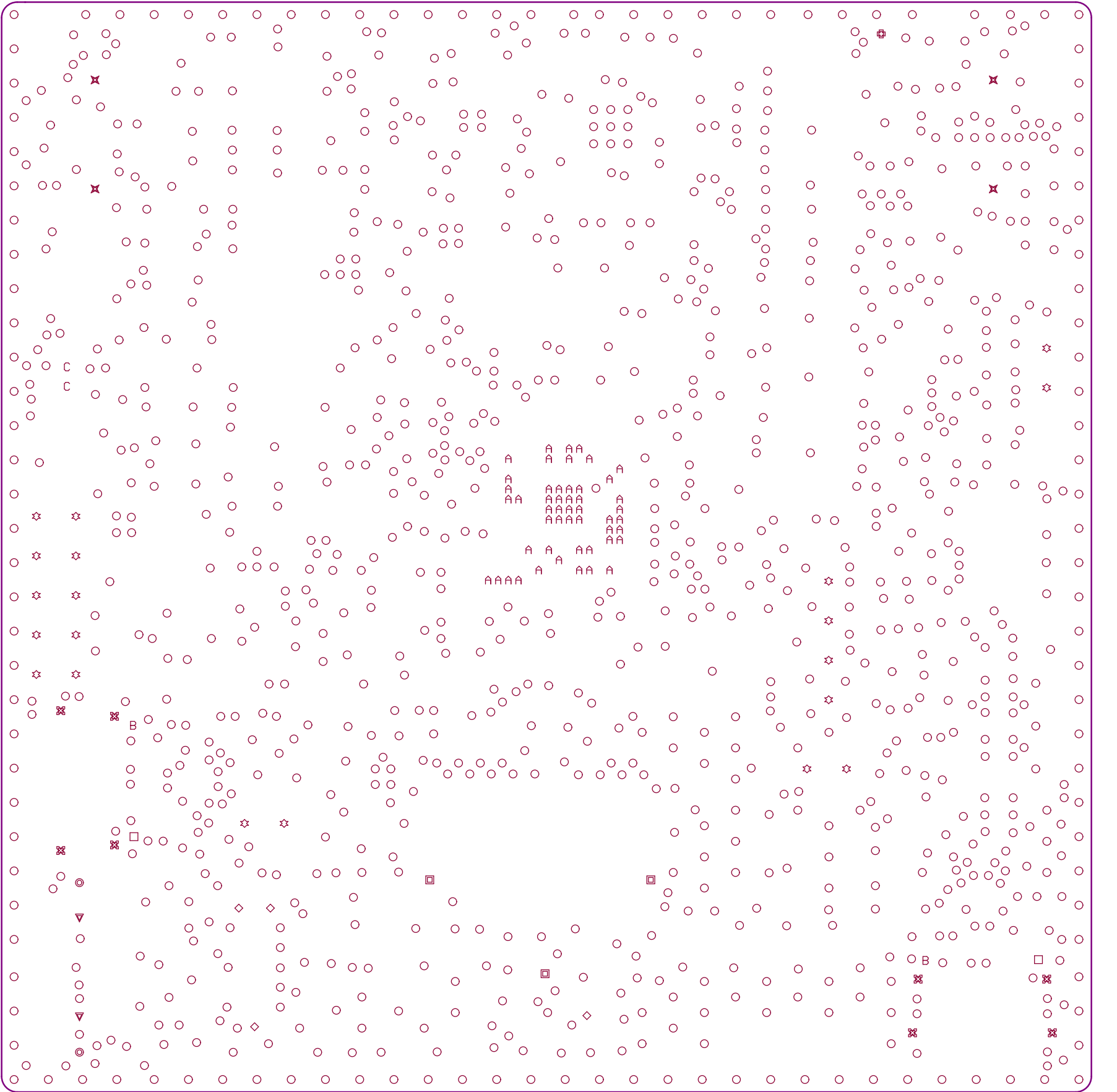
MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.12mm
GAPS : 0.12mm

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
DEFAULT
< 6:1
LEVEL "A"

STLink
6:1 A 8 : 1
LEVEL "B"



Symbol	Count	Via/Pad	Hole Size	Plated	Drill Layer Pair	Hole Type	Hole Length	Routed Path Length
	1	Pad	0.500mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	2	Pad	0.500mm	PTH	Top Layer - Bottom Layer	Round	-	-
	2	Pad	0.650mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	2	Pad	0.650mm	NPTH	Top Layer - Bottom Layer	Slot	0.950mm	0.300mm
	2	Pad	0.970mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	2	Pad	1.190mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	3	Pad	0.800mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	4	Pad	1.100mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	4	Pad	2.000mm	NPTH	Top Layer - Bottom Layer	Round	-	-
	8	Pad	0.500mm	PTH	Top Layer - Bottom Layer	Slot	1.100mm	0.600mm
	20	Pad	1.000mm	PTH	Top Layer - Bottom Layer	Round	-	-
	50	Via	0.200mm	PTH	Top Layer - Bottom Layer	Round	-	-
	1108	Via	0.300mm	PTH	Top Layer - Bottom Layer	Round	-	-
	1208 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: STM32WBA65I-DK1

Layer: Drill Drawing

Variant: [No Variations]

Date: 30-APRIL-24

Gerber: .DRL

Ref: MB2143

Rev: A